

Mechanical standardization of semiconductor devices —

Part 6-10: General rules for the preparation of outline drawings of surface mounted semiconductor device packages — Dimensions of P-VSON

The European Standard EN 60191-6-10:2003 has the status of a
British Standard

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National foreword

This British Standard is the official English language version of EN 60191-6-10:2003. It is identical with IEC 60191-6-10:2003.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors, which has the responsibility to:

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Summary of pages

This document comprises a front cover, an inside front cover, the EN title page, pages 2 to 12, an inside back cover and a back cover.

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Mechanical standardization of semiconductor devices
Part 6-10: General rules for the preparation of outline drawings of surface
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Dimensions of P-VSON
(IEC 60191-6-10:2003)

Normalisation mécanique des dispositifs
à semiconducteurs
Partie 6-10: Règles générales pour
la préparation des dessins
d'encombrement des dispositifs
à semiconducteurs pour montage
en surface –
Dimensions des boîtiers P-VSON
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Mechanische Normung von
Halbleiterbauelementen
Teil 6-10: Allgemeine Regeln für
die Erstellung von Gehäusezeichnungen
von SMD-Halbleitergehäusen -
P-VSON Gehäusemaße
(IEC 60191-6-10:2003)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
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Foreword

The text of document 47D/551/FDIS, future edition 1 of IEC 60191-6-10, prepared by SC 47D, Mechanical standardization of semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-10 on 2003-11-01.

The following dates were fixed:

- latest date by which the EN has to be implemented
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national standard or by endorsement (dop) 2004-08-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2006-11-01

Annexes designated "normative" are part of the body of the standard.
In this standard, annex ZA is normative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60191-6-10:2003 was approved by CENELEC as a European Standard without any modification.

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-10: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Dimensions of P-VSON

1 Scope

This part of IEC 60191 provides the common outline drawings and dimensions for all types of structures and composed materials of plastic very thin small outline non-lead package (hereinafter called P-VSON).

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191(all parts), *Mechanical standardization of semiconductor devices*

ISO/DIS 2692: *Geometrical Product Specification (GPS) – Geometrical tolerancing – Maximum material requirement (MMR) and least material requirement (LMR)*.

3 Terms and definitions

For the purposes of this document, the following definition, as well as those given in other parts of the IEC 60191 series, apply.

3.1 P-VSON

plastic very thin-profile small outline, flat package with no leads

NOTE The package leads (terminals) are on opposite sides of the bottom of the package body and do not extend beyond the package body.